

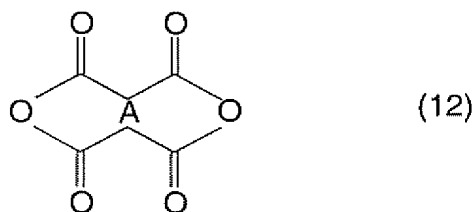
AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

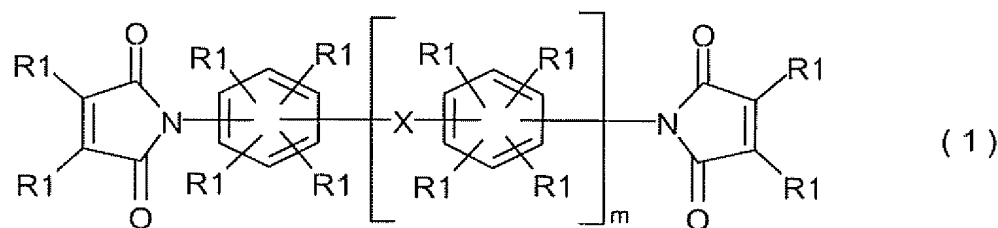
LISTING OF CLAIMS:

1. (Currently Amended) A metal laminate comprising:

a layer of a resin composition obtained by compounding a bismaleimide compound represented by the following formula (1) in a polyamic acid and/or a polyimide wherein the polyamic acid and/or a polyimide are/is obtained by reacting a diamine selected from the group consisting of 1,3-bis(3-(3-aminophenoxy)phenoxy)benzene, bis(3-(3-(3-aminophenoxy)phenoxy)phenyl) ether and 1,3-bis(3-(3-(3-aminophenoxy)phenoxy)phenoxy)benzene and tetracarboxylic dianhydride represented by the following formula (12):



wherein A represents a tetravalent organic group;



wherein m denotes an integer of 2 or more, each X independently represents O, SO₂, S, CO, or a direct bond and each R₁ independently represents a hydrogen atom, a halogen atom or a hydrocarbon group and is independent of any other as to the substitution position on the benzene ring in which X or N has a substitution position of meta to that of another X or N that is bonded to the same benzene ring;

a metal foil layer which is a rolled copper foil or an electrolytic copper foil,
and

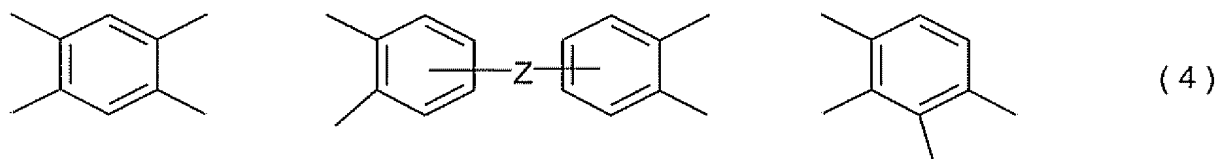
one or more polyimide film(s)

wherein the metal laminate has a structure in which the layer of the resin composition is formed on one surface or both surfaces of the one or more polyimide film(s) and the metal foil layer is formed on one surface or both surfaces of the layer of the resin composition and wherein the metal laminate is used as a base material for a chip-on-film or flexible substrate ~~and has a solder heat resistance of not less than 300°C.~~

2. (Canceled)

3. (Canceled)

4. (Currently Amended) The metal laminate according to Claim [[3]] 1, wherein the tetravalent organic group represented by A is selected from the organic groups represented by the following formulae shown in (4):



wherein Z represents O, SO₂, S, CO, CH₂, C(CH₃)₂, C(CF₃)₂ or a direct bond.

5. (Canceled)

6. (Canceled)

7. (Previously Presented) The metal laminate according to claim 1, wherein the metal foil layer has a thickness of equal to or less than 150 μm.

8. (New) The metal laminate according to claim 1, wherein the metal laminate has a solder heat resistance in the range of 300 to 360°C.

9. (New) The metal laminate according to claim 1, wherein the tetracarboxylic dianhydride is selected from the group consisting of 3,3',4,4'-benzophenonetetracarboxylic dianhydride, 3,3',4,4'-biphenyltetracarboxylic dianhydride, 3,3',4,4'-diphenyl ether tetracarboxylic dianhydride, and pyromellitic anhydride.